

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/05/2022

Details for "SN74AHCT138DBRG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74AHCT138DBRG4	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DB 16	5.3x6.2x1.95	418

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.114066	99.99737	999974	0.027286	273
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000877	9	0	0
Precious Metals	Silver	7440-22-4	0.000002	0.001753	18	0	0
Sub-Total			0.114069	100	1000000	0.027287	273
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.228962	80.00014	800001	0.054771	548
Thermoplastics	Epoxy	85954-11-6	0.05724	19.99986	199999	0.013693	137
Sub-Total			0.286202	100	1000000	0.068464	685
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	288.522125	97.248577	972486	69.019148	690191
Copper and Its Alloys	Iron	7439-89-6	7.7038	2.596624	25966	1.842873	18429
Copper and Its Alloys	Phosphorus	7723-14-0	0.044445	0.014981	150	0.010632	106
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.02963	0.009987	100	0.007088	71
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.08889	0.029961	300	0.021264	213
Zinc and Its Alloys	Zinc	7440-66-6	0.2963	0.09987	999	0.07088	709
Sub-Total			296.68519	100	1000000	70.971885	709719
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.370968	95.12	951200	0.088742	887
Precious Metals	Gold	7440-57-5	0.003042	0.78	7800	0.000728	7
Precious Metals	Palladium	7440-05-3	0.01599	4.1	41000	0.003825	38
Sub-Total			0.39	100	1000000	0.093294	933
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	105.266385	87.999999	880000	25.181418	251814
Other Plastics and Rubber	Carbon Black	1333-86-4	0.358863	0.3	3000	0.085846	858
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.657915	0.55	5500	0.157384	1574
Thermoplastics	Epoxy	85954-11-6	13.33773	11.15	111500	3.1906	31906
Sub-Total			119.620893	100	1000000	28.615248	286152
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.935646	100	1000000	0.223822	2238
Sub-Total			0.935646	100	1000000	0.223822	2238
Total			418.032			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 06/05/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.